易灵思®

钛金系列 FPGA Selector Guide


35K to 1,000K Logic Elements


10 Kb Embedded RAM Blocks


DSP Blocks


PLLs


High-Voltage I/O (HVIO)


High-Speed I/O (HSIO)


MIPI D-PHY 2.5 Gbps


DDR4, LPDDR4 Controller & PHY


SerDes 16G/25.8G

钛金系列 Ordering Codes

You can use HSIO pairs for a various differential standards such as LVDS (1.6 Gbps), differential HSTL/SSTL, or MIPI RX and TX data/clock lanes (1.5 Gbps).

FPGA	LEs	RAM (kbits)	RAM Blocks (10 Kb)	DSP Blocks	Package	Pins	HVIO	HSIO	PLLs	2.5G MIPI D-PHY	DDR	16G SerDes	PCIe Gen4	25.8G SerDes	Temperature	Speed Grade	Ordering Code
Ti35	36,176	1.53	49	93	FBGA	100	–	61	3	–	–	–	–	–	C	3, 4	Ti35F100S3F2C3/4
															I	4	Ti35F100S3F2I4
					FBGA	225	23	140	4	–	–	–	–	–	C	3, 4	Ti35F225C3/4
															I	4	Ti35F225I4
Ti60	62,016	2.6	256	160	WLCSP	64	–	35	2	–	–	–	–	–	I	4	Ti60W64I4
					FBGA	100	–	61	3	–	–	–	–	–	C	3, 4	Ti60F100S3F2C3/4
															I	4	Ti60F100S3F2I4
					FBGA	225	23	140	4	–	–	–	–	–	C	3, 4	Ti60F225C3/4
															I	4	Ti60F225I4

Package Dimensions

Package	Pitch	Dimensions (mm)
64-ball FBGA	0.4	3.5x3.4
100-ball FBGA	0.5	5.5x5.5
225-ball FBGA	0.5	8x8

Example Ordering Code

钛金系列 **FPGA** — **Ti60 F225 C 3**

Package Code

Speed Grade
3, 4

Operating Temperature
C: Commercial (T_J = 0° C to 85° C)
I: Industrial (T_J = -40° C to 100° C)

Some ordering codes include extra characters in the package code to designate additional components in the package. For example, the Ti60 in the F100 package has HyperRAM and flash as indicated by the S3F2 in the package code.

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